

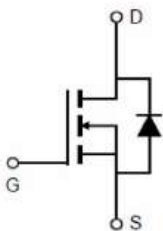
MJ N-Channel Enhancement Mode Power MOSFET

Description

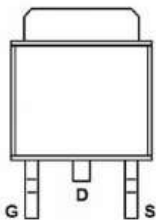
The MJ4528K uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge .
The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

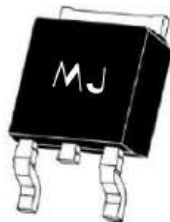
- ◆ **N-Channel**
 $V_{DS} = 45V, I_D = 28A$
 $R_{DS(ON)} < 19m\Omega @ V_{GS} = 10V$
 $R_{DS(ON)} < 28m\Omega @ V_{GS} = 4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package



Schematic diagram



Marking and pin assignment



TO-252-2L top view

100% UIS TESTED! 100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|---------|----------------|-----------|------------|----------|
| MJ4528K | MJ4528K | TO-252-2L | - | - | - |

Absolute Maximum Ratings ($T_c = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|---------------------------------------------------------|------------------------------|------------|--------------------|
| Drain-Source Voltage | V_{DS} | 45 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 28 | A |
| Drain Current-Continuous($T_c = 100^{\circ}\text{C}$) | $I_{D(100^{\circ}\text{C})}$ | 21.2 | A |
| Pulsed Drain Current ^(Note 1) | I_{DM} | 100 | A |
| Maximum Power Dissipation | P_D | 45 | W |
| Single pulse avalanche energy ^(Note 5) | E_{AS} | 90 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | $^{\circ}\text{C}$ |

Thermal Characteristic

| | | | |
|----------------------------------------------------------|-----------------|-----|----------------------|
| Thermal Resistance, Junction-to-Case ^(Note 2) | $R_{\theta JC}$ | 3.3 | $^{\circ}\text{C/W}$ |
|----------------------------------------------------------|-----------------|-----|----------------------|

N-CH Electrical Characteristics (T_A=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---------------------------------------------------|---------------------|-----------------------------------------------------------------------------------------|-----|------|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | 45 | - | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =45V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{DS} =±20V,V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics <small>(Note 3)</small> | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250μA | 1.0 | 1.5 | 2.0 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =20A | - | 14.5 | 19 | mΩ |
| | | V _{GS} =4.5V, I _D =15A | - | 19 | 28 | mΩ |
| Forward Transconductance | g _{FS} | V _{DS} =5V,I _D =20A | 33 | - | - | S |
| Dynamic Characteristics <small>(Note 4)</small> | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =20V,V _{GS} =0V F=1.0MHz | - | 964 | - | PF |
| Output Capacitance | C _{Oss} | | - | 109 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | | - | 96 | - | PF |
| Switching Characteristics <small>(Note 4)</small> | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =20V, R _L =2.5Ω V _{GS} =10V,R _{GEN} =3Ω | - | 5.5 | - | nS |
| Turn-on Rise Time | t _r | | - | 14 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | - | 24 | - | nS |
| Turn-Off Fall Time | t _f | | - | 12 | - | nS |
| Total Gate Charge | Q _g | V _{DS} =20V,I _D =20A V _{GS} =10V | - | 22.9 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 3.5 | - | nC |
| Gate-Drain Charge | Q _{gd} | | - | 5.3 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage <small>(Note 3)</small> | V _{SD} | V _{GS} =0V,I _S =20A | - | 0.8 | 1.2 | V |

Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production
- ⑤ EAS condition: T_j=25°C, V_{DD}=20V, V_G=10V, L=0.5mH, R_g=25Ω

N- Channel Typical Electrical and Thermal Characteristics (Curves)

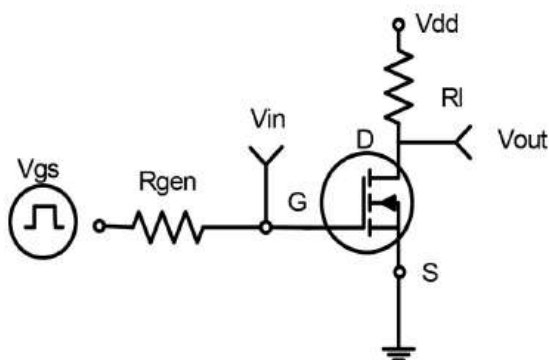


Figure 1 Switching Test Circuit

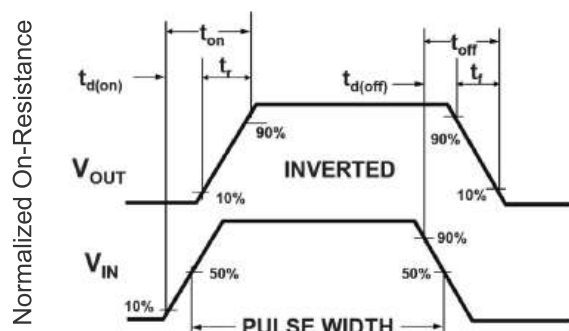


Figure 2 Switching Waveforms

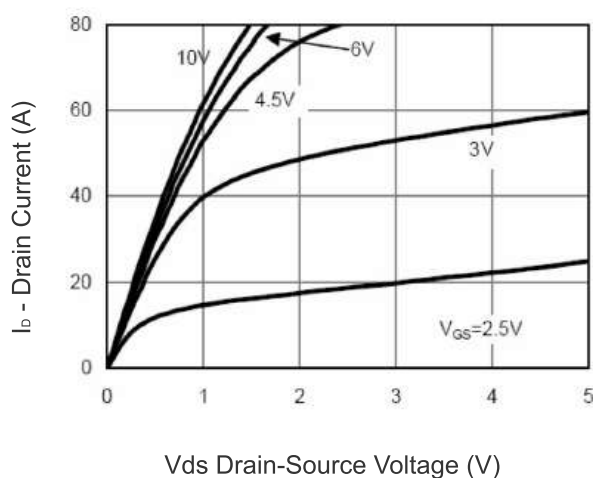


Figure 3 Output Characteristics

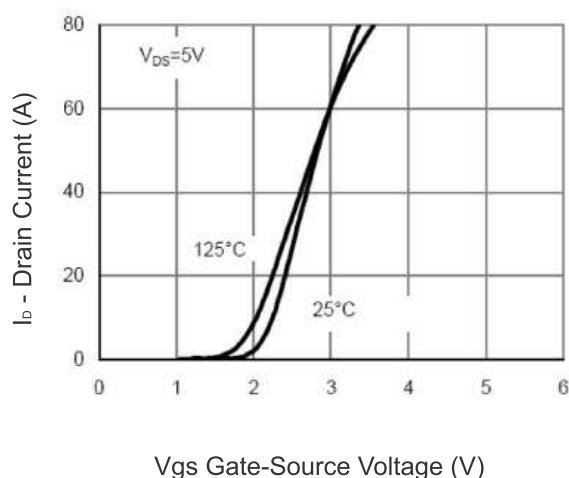


Figure 4 Transfer Characteristics

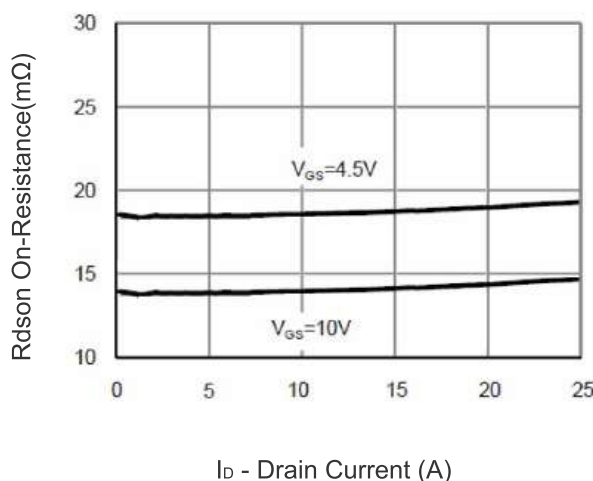


Figure 5 Drain-Source On-Resistance

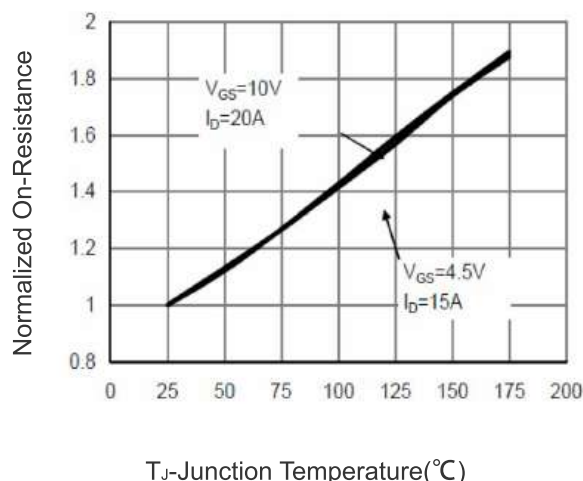
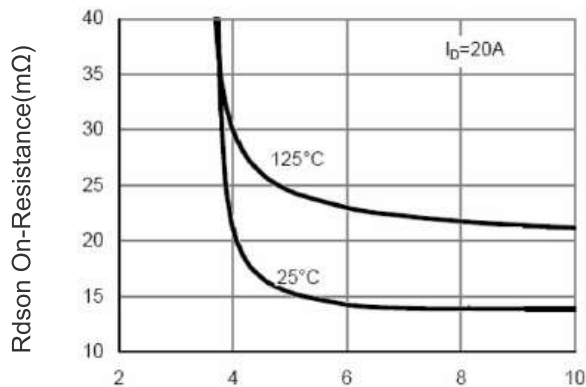
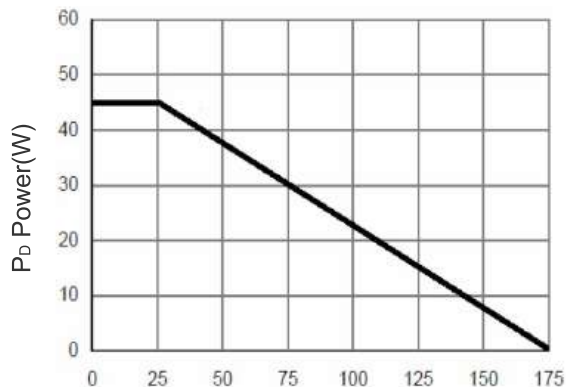


Figure 6 Drain-Source On-Resistance



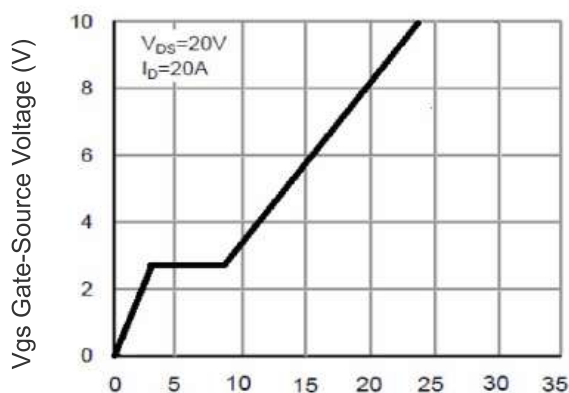
Vgs Gate-Source Voltage (V)

Figure 7 Rdson vs Vgs



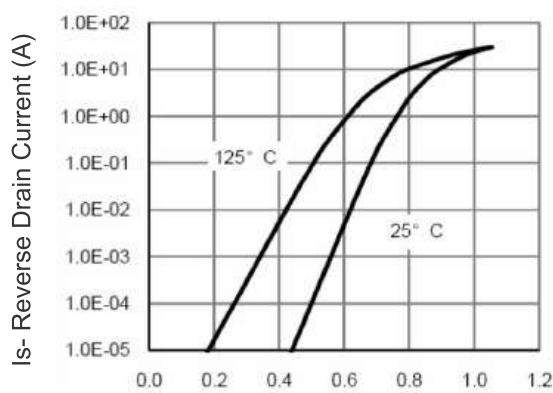
Tj-Junction Temperature(°C)

Figure 8 Power Dissipation



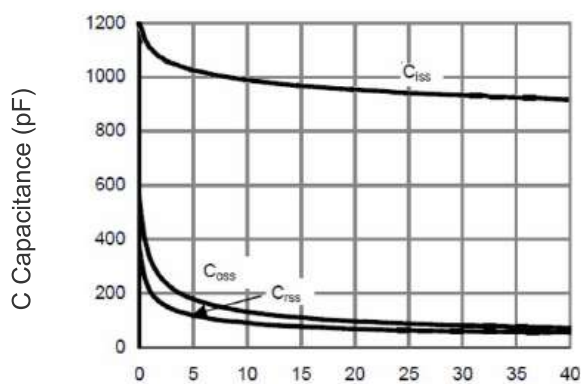
Qg Gate Charge (nC)

Figure 9 Gate Charge



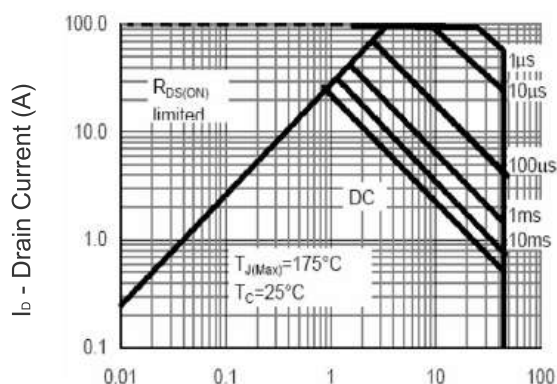
Vds Drain-Source Voltage (V)

Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)

Figure 11 Capacitance vs Vds



Vds Drain-Source Voltage (V)

Figure 12 Safe Operation Area

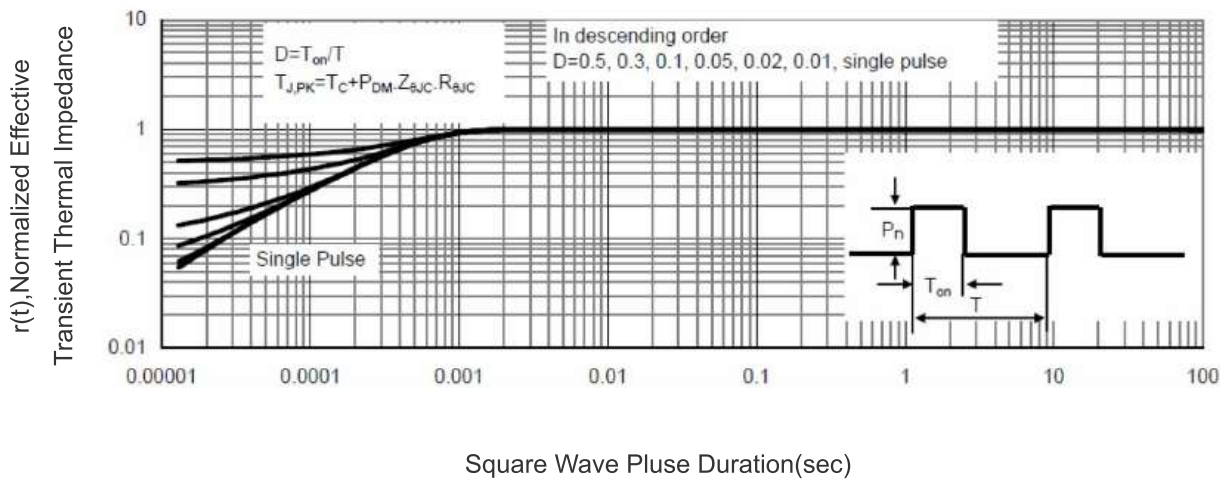
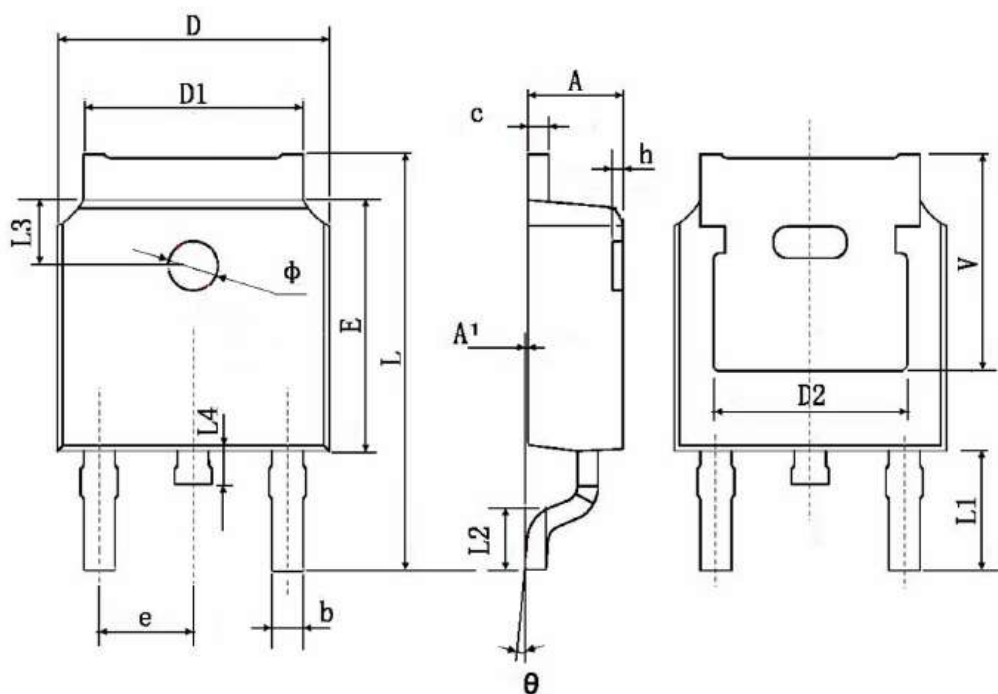


Figure 13 Normalized Maximum Transient Thermal Impedance

TO-252 Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| b | 0.660 | 0.860 | 0.026 | 0.034 |
| c | 0.460 | 0.580 | 0.018 | 0.023 |
| D | 6.500 | 6.700 | 0.256 | 0.264 |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 |
| D2 | 4.83 TYP. | | 0.190 TYP. | |
| E | 6.000 | 6.200 | 0.236 | 0.244 |
| e | 2.186 | 2.386 | 0.086 | 0.094 |
| L | 9.800 | 10.400 | 0.386 | 0.409 |
| L1 | 2.900 TYP. | | 0.114 TYP. | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 |
| L3 | 1.600 TYP. | | 0.063 TYP. | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 |
| Φ | 1.100 | 1.300 | 0.043 | 0.051 |
| θ | 0° | 8° | 0° | 8° |
| h | 0.000 | 0.300 | 0.000 | 0.012 |
| V | 5.350 TYP. | | 0.211 TYP. | |

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